

SPECIFICATIONS					
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:	(This Code will be changed while mass production) PG12864LRS-DNN-H (VER.0)				
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Sales Sign	QC Confirmed	Checked By	Designer
		Tom 2003/08/20 能明生	新成考 2003/08/18

Approval For Specifications Only.

* This specification is subject to change without notice.

Please contact Powertip or it's representative before designing your product based on this specification.

Approval For Specifications and Sample.

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RECORDS OF REVISION

Date	Rev.	Description	Note	Page
2003/08/11	0	Revised Contents		

Total: 23 Page



Contents

1. SPECIFICATIONS

- **1.1 Features**
- **1.2 Mechanical Specifications**
- **1.3 Absolute Maximum Ratings**
- **1.4 DC Electrical Characteristics**
- **1.5 Optical Characteristics**
- **1.6 Backlight Characteristics**

2. MODULE STRUCTURE

- 2.1 Counter Drawing
- 2.2 Interface Pin Description
- 2.3 Timing Characteristics
- 2.4 Display Command

3. QUALITY ASSURANCE SYSTEM

- 3.1 Quality Assurance Flow Chart
- **3.2 Inspection Specification**

4. RELIABILITY TEST

4.1 Reliability Test Condition

5. PRECAUTION RELATING PRODUCT HANDLING

- 5.1 Safety
- 5.2 Handling
- 5.3 Storage
- 5.4 Terms of Warranty

Note : For detailed information please refer to IC data sheet : <u>KS107,KS108</u>

1. SPECIFICATIONS

1.1 Features

Item	Standard Value
Display Type	128 * 64 dots
LCD Type	STN, Gray, Transflective, Positive, Extended Temp.
Driver Condition	LCM Module:1/64 Duty , 1/9 Bias
Viewing Direction	6 O' clock
Backlight	Yellow-green LED B/L
Weight	52 g
Interface	-
Other	_

1.2 Mechanical Specifications

Item	Standard Value	Unit
Outline Dimension	84.0(L) *60.0(w) * 11.4(H)(Max)	mm
Viewing Area	59.4(L) * 38.0(w)	mm
Active Area	56.28(L) * 33.24(w)	mm
Dot Size	0.40(L) * 0.48(w)	mm
Dot Pitch	0.44(L) * 0.52(w)	mm

Note: For detailed information please refer to LCM drawing

1.3 Absolute Maximum Ratings

Item	Symbol	Condition	Min.	Max.	Unit
Power Supply Voltage	V _{DD}	-	-0.3	7.0	V
LCD Driver Supply Voltage	V _{LCD}	-	VDD-19.0	VDD+0.3	V
Input Voltage	V _{IN}	-	-0.3	V _{DD} +0.3	V
Operating Temperature	T _{OP}	Excluded B/L	-20	70	
Storage Temperature	T _{ST}	Excluded B/L	-30	80	
Storage Humidity	H _D	Ta < 40	-	90	%RH



1.4 DC Electrical Characteristics

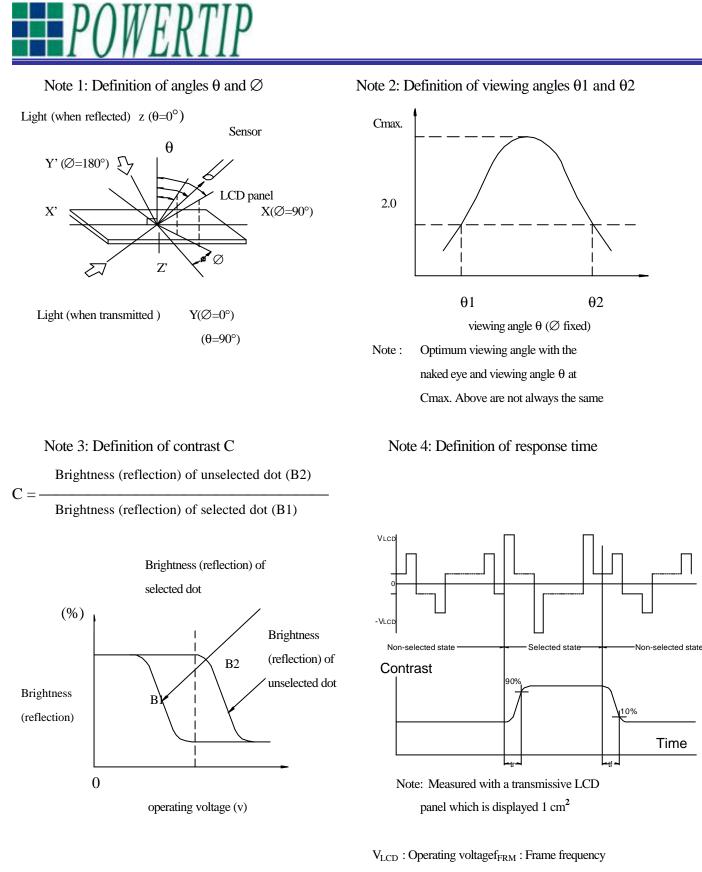
	$V_{DD} = 5.0 \ V \pm 10\%$, $V_{SS} = 0 V$, $Ta = 25$					
Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Logic Supply Voltage	V _{DD}	-	4.5	5.0	5.5	V
"H" Input Voltage	V _{IH}	-	0.7 V dd	-	Vdd	V
"L" Input Voltage	V _{IL}	-	Vss	-	0.3 V dd	V
"H" Output Voltage	V _{OH}	-	Vdd-0.4	-	-	V
"L" Output Voltage	V _{OL}	-	-	-	0.4	V
Supply Current	I _{DD}	V _{DD} = 5.0 V	-	2.0	-	mA
		-20°C	-	-	-	
LCM Driver Voltage	V _{OP}	25°C 1 *	-	13.8	-	V
		70°C	-	-	-	

Note: *1 The Vop Test Point is VDD-Vo.

1.5 Optical Characteristics

LCD Panel : 1/64 Duty , 1/9 Bias , $V_{\rm LCD}$ =13.3V , Ta = 25

Item	Symbol	Conditions	Min.	Тур.	Max.	Reference
View Angle	è	C \geq 2.0, Ø = 0°	40°	-	-	Notes 1 & 2
Contrast Ratio	С	$\dot{e} = 5^{\circ}, \emptyset = 0^{\circ}$	5	7	-	Note 3
Response Time(rise)	tr	$\dot{e} = 5^{\circ}, \emptyset = 0^{\circ}$	-	150ms	-	Note 4
Response Time(fall)	tf	$\dot{e} = 5^{\circ}, \emptyset = 0^{\circ}$	-	300ms	-	Note 4





1.6 Backlight Characteristics

LCD Module with LED Backlight

Maximum Ratings

ltem	Symbol	Conditions	Min.	Max.	Unit
Forward Current	F	Ta =25	-	250	mA
Reverse Voltage	VR	Ta =25	-	8	V
Power Dissipation	PO	Ta =25	-	1.1	W
Operating Temperature	T _{OP}	-	-20	70	
Storage Temperature	T _{ST}	-	-40	80	
Solder Temp. for 3 Second	-	-	-	260	

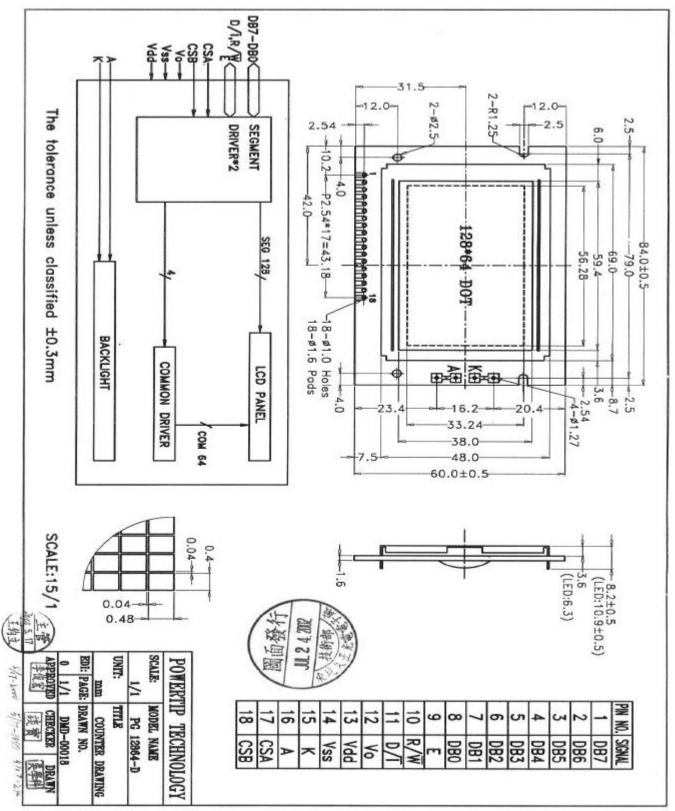
Electrical / Optical Characteristics

					Ta =	25
Item	Symbol	Conditions	Min.	Тур.	Max.	Unit
Forward Voltage	VF	IF= 100 mA	3.6	4.0	4.4	V
Reverse Current	IR	VR= 8 V	-	-	0.2	mA
Wavelength	р	IF= 100 mA	571	-	576	nm
Luminous Intensity (without LCD)	N	IF=100 mA	14	18	-	cd/m ²
Color	Yellow-green					



2. MODULE STRUCTURE

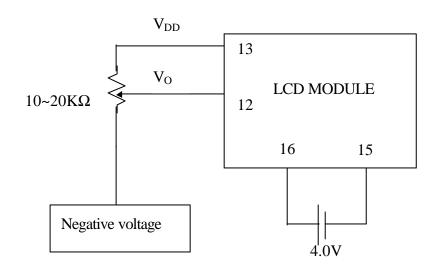
2.1 Counter Drawing



2.2 Interface Pin Description

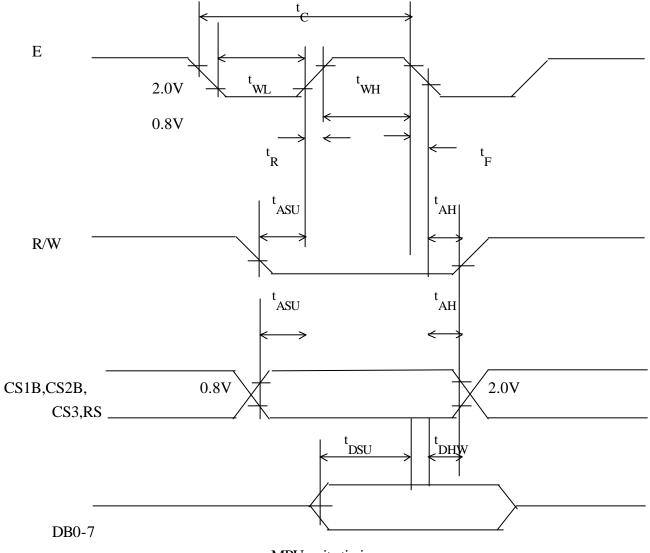
Pin No.	Symbol	Function			
1-8	DB7~DB0	Data Bus (Three State I/O common terminal)			
		Enable signal			
		Write mode (R/W=L): Data of DB (0:7) is latched at			
9	Е	the falling edge of E.			
		Read mode (R/W=H):DB (0:7) appears the reading			
		data while E is at high level			
		Read or write.			
		$R/\overline{W}=H$ Data appears at DB<0:7> and can be read			
10	R/W	by the CPU while E=H, CSA=L or CSB=L.			
		R/W=L Display data (DB<0:7>) can be written at falling			
		of E when CSA=L or CSB=L.			
		Data or Instruction.			
11	D/I	D/I=H DB<0:7>:Display RAM Data			
		D/I=L DB<0:7> :Instruction Data			
12	Vo	Operating voltage (LCD Driver)			
13	VDD	Power Supply (V _{DD} >V _{SS})			
14	Vss	Power Supply (Vss=0)			
15	K	Power supply LED backlight (-)			
16	А	Power supply LED backlight (+)			
17	CSA	Chip enable for D2 (segment 1 to segment 64)			
18	CSB	Chip enable for D3 (segment 65 to segment 128)			

Contrast Adjust

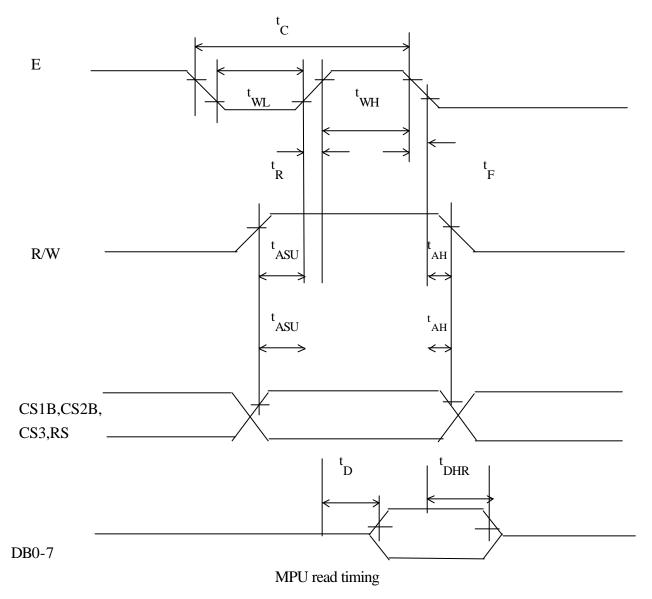




2.3 Timing Characteristics



MPU write timing





Characteristic	Symbol	Min.	Тур	Max	Unit
E Cycle	Tc	1000	-	-	ns
E High Level Width	twн	450	-	-	ns
E Low Level Width	twL	450	-	-	ns
E Rise Time	Tr	-	-	25	ns
E Fall Time	TF	-	-	25	ns
Address Set-Up time	tasu	140	-	-	ns
Address Hold Time	tан	10	-	-	ns
Data Set-Up Time	tdsu	200		-	ns
Data Delay Time	TD	-	-	320	ns
Data Hold Time (Write)	tDHW	10	-	-	ns
Data Hold Time (Read)	tdhr	20	-	-	ns



2.4 Display command

Instructions	RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0	Functions
											Controls the display on or
Display on/off	0	0	0	0	1	1	1	1	1	0/1	Off. Internal status and
											display RAM data is not
									affected.		
											0: OFF , 1: ON
Set address	0	0	0	1			Y ad	dress			Sets the Y address in the Y
(Y address)							(0~	63)			address counter.
Set Page	0	0	1	0	1	1	1		Page		Sets the X address at the
(X address)									(0-7)		X register.
Display Start Line	0	0	1	1		D	visplay	start lir	ne		Indicates the display data
(Z address)							(0~	63)			RAM displayed at the top
											of the screen.
	0	1	В	0	0	R	0	0	0	0	Reads status.
			U		Ν	Е					BUSY 1 : In operation
			S		/	S					0 : Ready
Status Read			Y		0	Е					ON/OFF 1 : Display OFF
					F	Т					0 : Display ON
					F						RESET 1 : Reset
											0 : Normal
											Writes data (DB0:7) into
											display data RAM. After
Write Display Data	1	0				Write	Data				writing instruction, Y
											address is increased by 1
											automatically.
											Reads data (DB0:7) from
Read Display Data	1	1			Read Data						display data RAM to the
										data bus.	
Detailed Exp	lanatio	on									

Display On/Off

	RS R/W		DB7DB0				0			
Code	0	0	0	0	1	1	1	1	1	D

The display data appears when D is 1 and disappears when D is 0. Though the data is not on the screen with D=0, it remains in the display data RAM. Therefore, you can make it appear by changing D=0 into D=1.

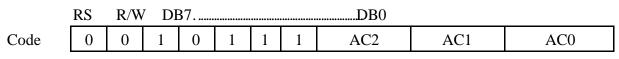


Display Start Line (Z Address)

	RS	R/W	DB7	• •••••	••••••)			
Code	0	0	1	1	AC5	AC4	AC3	AC2	AC1	AC0

Z address(AC0-AC5) of the display data RAM is set in the display start line register and displayed at the top of the screen. When the display duty cycle is 1/64 or others(1/32-1/64), the data of total line number of LCD screen, form the line specified by display start line instruction, is displayed. See figure 1.

Set page (X address)



X address (AC0-AC2) of the display data RAM is set in the X address register. Writing or reading to or from MPU is executed in this specified page until the next page is set. See figure 2.

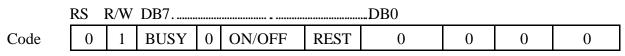
Set Adress (Y Address)

	RS	R/W	DI	37	••••••					
Code	0	0	0	1	AC5	AC4	AC3	AC2	AC1	AC0

Y address(AC0-AC5) of the display data RAM is set in the Y address Counter. An address is set by instruction and increased

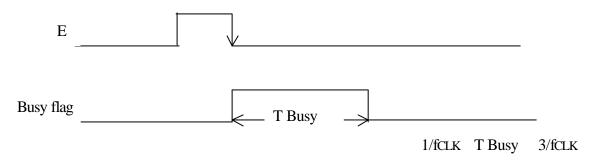
by 1 automatically by read or write operations of display data.

<u>Status Read</u>



• Busy

When busy is 1, the Chip is executing internal operation and no instructions are accepted When busy is 0, the Chip is ready to accept any instructions.





• ON/OFF

When on/off is 1, the display is OFF.

When on/off is 0, the display is ON.

• RESET

When RESET is 1, the system is being initialized.

In this condition, no instructions except status read can be accepted.

When RESET is 0, initializing has finished and the system is in the usual operation condition.

Write Display Data

	RS	R/W DB7					DB0			
Code	0	1	D7	D6	D5	D4	D3	D2	D1	D0

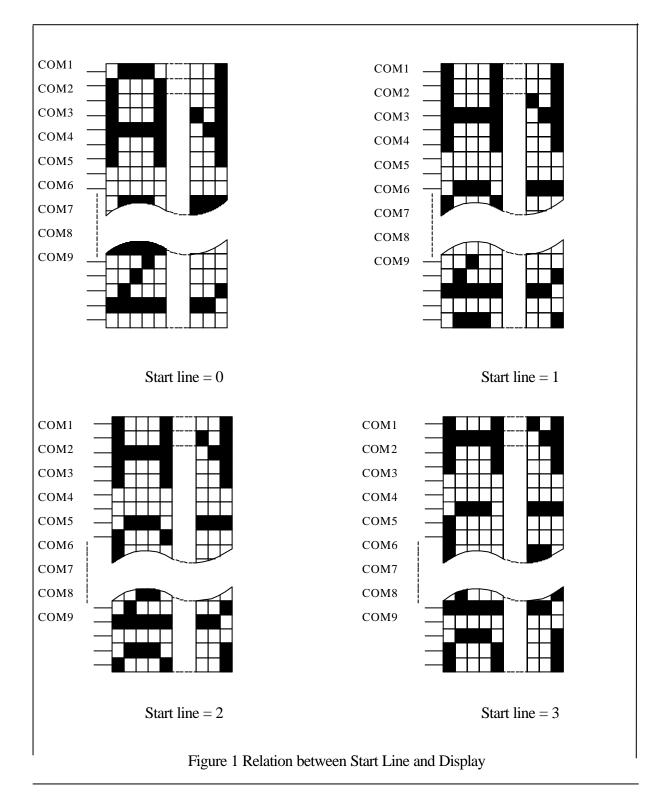
Write data(D0-D7) into the display data RAM.After writing instruction, Y address is increased by 1 automatically.

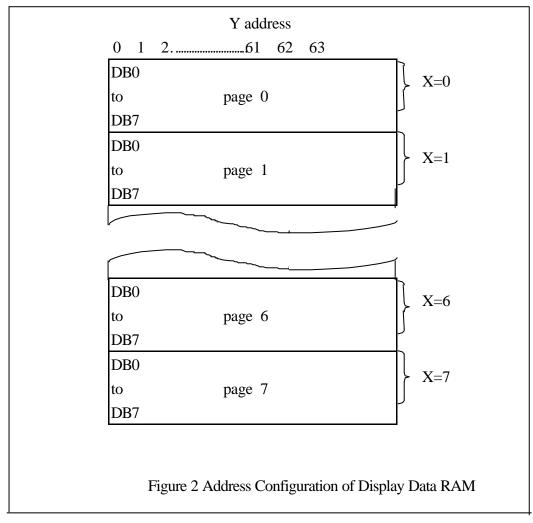
Read Display Data

	R/W	D/I	DB7							
Code	1	1	D7	D6	D5	D4	D3	D2	D1	D0

Reads data(D0-D7) from the display data RAM. After reading instruction, Y address is increased by 1 automatically







Note: "128*64" consist of 2 "64*64"

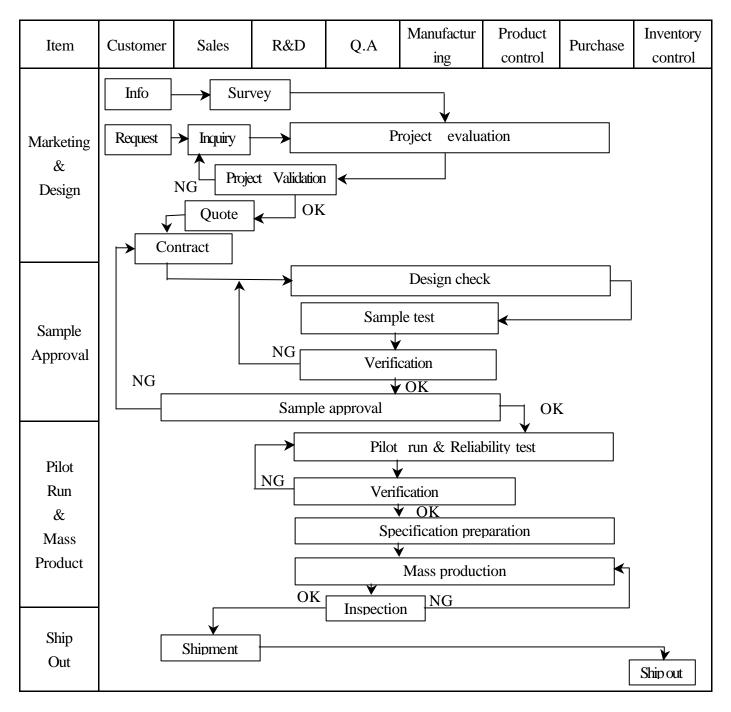
 $CS1 \Rightarrow$ Chip enable for left 64*64 (segment1 to segment 64)

 $CS2 \Rightarrow$ Chip enable for right 64*64 (segment 65 to segment 128)

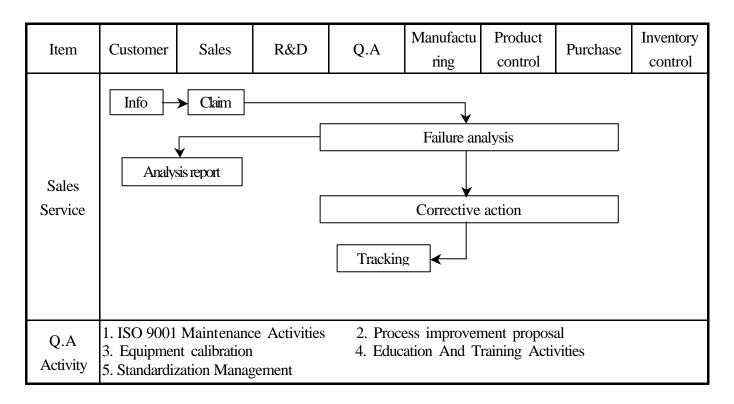


3. QUALITY ASSURANCE SYSTEM

3.1 Quality Assurance Flow Chart







3.2 Inspection Specification

Inspection Standard : MIL-STD-105E Table Normal Inspection Single Sampling Level Equipment : Gauge, MIL-STD, Powertip Tester, Sample,

o

IQC Defect Level : Major Defect AQL 0.4; Minor Defect AQL 1.5_{\circ}

FQC Defect Level: 100% Inspection.

OUT Going Defect Level : Sampling.

Specification :

NO	Item	Specification	Judge	Level
1	Part Number	The part number is inconsistent with work order of production	N.G.	Major
2	Quantity	The quantity is inconsistent with work order of production	N.G.	Major
	Electronic	The display lacks of some patterns.	N.G.	Major
	characteristics of	Missing line.	N.G.	Major
3	LCM	The size of missing det A is $> 1/2$ Det size		Major
	$A=(L+W) \div 2$	There is no function.	N.G.	Major
	· · ·	Output data is error	N.G.	Major
		Material is different with work order of production	N.G.	Major
		LCD is assembled in inverse direction	N.G.	Major
		Bezel is assembled in inverse direction	N.G.	Major
		Shadow is within LCD viewing area + 0.5 mm	N.G.	Major
	Appearance of	The diameter of dirty particle, A is > 0.4 mm	N.G.	Minor
	$\begin{array}{c} \text{LCD} \\ \text{A=}(\text{L} + \text{W}) \div 2 \end{array}$	Dirty particle length is > 3.0mm, and 0.01mm < width 0.05mm	N.G.	Minor
4	D' ()	Display is without protective film	N.G.	Minor
	Dirty particle (Including	Conductive rubber is over bezel 1mm	N.G.	Minor
	scratch, bubble)	Polarizer exceeds over viewing area of LCD	N.G.	Minor
	scratcik bubble)	Area of bubble in polarizer, $A > 1.0$ mm, the number of bubble is > 1 piece.	N.G.	Minor
		0.4mm < Area of bubble in polarizer, A < 1.0mm, the number of bubble is > 4 pieces.	N.G.	Minor
		Burned area or wrong part number is on PCB	N.G.	Major
		The symbol, character, and mark of PCB are unidentifiable.	N.G	Minor
		The stripped solder mask , A is > 1.0 mm	N.G.	Minor
_	Appearance of	0.3mm < stripped solder mask or visible circuit, A < 1.0mm, and the number is 4 pieces	N.G.	Minor
5	PCB	There is particle between the circuits in solder mask	N.G	Minor
	$A=(L+W) \div 2$	$A = (L + W) \div 2$ The circuit is peeled off or cracked		
		There is any circuits risen or exposed.	N.G	Minor
		0.2mm < Area of solder ball, A is 0.4mm The number of solder ball is 3 pieces	N.G	Minor
		The magnitude of solder ball, A is > 0.4 mm.	N.G	Minor

NO	Item	Specification	Judge	Level
		The shape of modeling is deformed by touching.	N.G.	Major
	Appearance of	Insufficient epoxy: Circuit or pad of IC is visible	N.G.	Minor
6	molding	Excessive epoxy: Diameter of modeling is > 20mm	NC	Minor
	$A=(L+W) \div 2$	or height is > 2.5mm	N.G.	Minor
		The diameter of pinhole in modeling, A is > 0.2 mm.	N.G.	Minor
		The folding angle of frame must be $> 45 + 10$	N.G.	Minor
	Appearance of frame	The area of stripped electroplate in top-view of frame, A is > 1.0 mm.	N.G.	Minor
7	$A=(L+W) \div 2$	Rust or crack is (Top view only)	N.G.	Minor
		The scratched width of frame is > 0.06 mm.	11.0.	IVIIIIOI
		(Top view only)	N.G.	Minor
	Electrical characteristic of	The color of backlight is nonconforming	N.G.	Major
		Backlight can't work normally.	N.G.	Major
8	backlight	The LED lamp can't work normally	N.G.	Major
0	$A=(L+W) \div 2$	The unsoldering area of pin for backlight,		Minor
		A is $> 1/2$ solder joint area.	N.G.	
	$\Pi^{-}(\mathbf{L} + \mathbf{W}) : \mathbf{Z}$	The height of solder pin for backlight is > 2.0 mm	N.G.	Minor
		The mark or polarity of component is unidentifiable.	N.G.	Minor
		The height between bottom of component and	N.G.	Minor
		surface of the PCB is floating > 0.7mm	11.0.	TANITO
10	Assembly parts A=(L+W) $\div 2$	D > 1/4W W $D\downarrow\downarrow\downarrow\downarrow\downarrow\downarrow\downarrow\downarrow$	N.G.	Minor
		End solder joint width, D' is $> 50\%$ width of component termination or width of pad	N.G.	Minor
		Side overhang, D is $> 25\%$ width of component termination.	N.G.	Minor
		Component is cracked, deformed, and burned, etc.	N.G.	Minor
		The polarity of component is placed in inverse direction.	N.G.	Minor
		Maximum fillet height of solder extends onto the component body or minimum fillet height is < 0.5mm.	N.G.	Minor



4. RELIABILITY TEST

4.1 Reliability Test Condition

NO	Item	Test Co	ondition				
1	High Temperature Storage	Storage at 80 ± 2 96~100 hrs Surrounding temperature, then storag 4hrs	ge at normal condition				
2	Low Temperature Storage	Storage at -30 \pm 2 96~100 hrs Surrounding temperature, then storage at normal condition 4hrs					
3	High Temperature /Humidity Storage	 1.Storage 96~100 hrs 60 ± 2 , 90~95%RH surrounding temperature, then storage at normal condition 4hrs. (Excluding the polarizer). or 2.Storage 96~100 hrs 40 ± 2 , 90~95%RH surrounding temperature, then storage at normal condition 4 hrs. 					
4	Temperature Cycling	-20 25 70 25 (30mins) (5mins) (30mins) (5mins) 10 Cycle					
5	Vibration	```	ninute) 1.5mm fon * (each 2hrs)				
6	ESD Test	Air Discharge: Apply 6 KV with 5 times discharge for each polarity +/- Testing location: Around the face of LCD	Contact Discharge: Apply 250V with 5 times discharge for each polarity +/- Testing location: 1.Apply to bezel. 2.Apply to Vdd, Vss.				
7	Drop Test	Packing Weight (Kg) 0 ~ 45.4 45.4 ~ 90.8 90.8 ~ 454 Over 454	Drop Height (cm) 122 76 61 46				



5. PRECAUTION RELATING PRODUCT HANDLING

5.1 SAFETY

- 5.1.1 If the LCD panel breaks, be careful not to get the liquid crystal to touch your skin.
- 5.1.2 If the liquid crystal touches your skin or clothes, please wash it off immediately by using soap and water.

5.2 HANDLING

- 5.2.1 Avoid any strong mechanical shock which can break the glass.
- 5.2.2 Avoid static electricity which can damage the CMOS LSI–When working with the module , be sure to ground your body and any electrical equipment you may be using.
- 5.2.3 Do not remove the panel or frame from the module.
- 5.2.4 The polarizing plate of the display is very fragile. So , please handle it very carefully ,do not touch , push or rub the exposed polarizing with anything harder than an HB pencil lead (glass , tweezers , etc.)
 - 5.2.5 Do not wipe the polarizing plate with a dry cloth, as it may easily scratch the surface of plate.
- 5.2.6 Do not touch the display area with bare hands , this will stain the display area.
- 5.2.7 Do not use ketonics solvent & aromatic solvent. Use with a soft cloth soaked with a cleaning naphtha solvent.
- 5.2.8 To control temperature and time of soldering is 280 ± 10 and 3-5 sec.
- 5.2.9 To avoid liquid (include organic solvent) stained on LCM .

5.3 STORAGE

- 5.3.1 Store the panel or module in a dark place where the temperature is 25 ± 5 and the humidity is below 65% RH.
- 5.3.2 Do not place the module near organics solvents or corrosive gases.
- 5.3.3 Do not crush , shake , or jolt the module.

5.4 TERMS OF WARRANTY

5.4.1 Applicable warrant period

The period is within thirteen months since the date of shipping out under normal using and storage conditions.

5.4.2 Unaccepted responsibility

This product has been manufactured to your company's specification as a part for use in your company's general electronic products. It is guaranteed to perform according to delivery specifications. For any other use apart from general electronic equipment, we cannot take responsibility if the product is used in nuclear power control equipment, aerospace equipment, fire and security systems or any other applications in which there is a direct risk to human life and where extremely high levels of reliability are required.